



2.0A SURFACE MOUNT ULTRA-FAST RECTIFIER

Product Summary (@TA = +25°C)

V _{RRM} (V)	I _O (A)	V _F (MAX) (V)	I _{R(MAX)} (μA)
600	2	1.7	5

Features and Benefits

- Glass Passivated Die Construction
- Ultra-Fast Recovery Time for High Efficiency
- Surge Overload Rating to 50A Peak
- High Current Capability
- Low Profile Design, Package Height Less than 1.1mm
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standard for High Reliability
- PPAP Capable (Note 4)

Description and Applications

The US2JDFQ is a rectifier packaged in the low-profile D-FLAT package. Providing ultra-fast recovery time for high efficiency, this device is ideal for use in applications, such as:

- Reverse Protection
- Switching
- Blocking

Mechanical Data

- Case: D-FLAT
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish—Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 (3)
- Polarity: Cathode Band
- Weight: 0.036 grams (Approximate)

D-FLAT



Top View

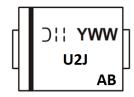
Ordering Information (Note 5)

Part Number	Qualification	Case	Packaging
US2JDFQ-13	Automotive	D-FLAT	10,000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



U2J= Product Type Marking Code

O!! = Manufacturer's Code Marking

YWW = Date Code Marking

Y = Last Digit of Year (ex: 4 for 2014)

WW = Week Code (01 to 53)

AB = Foundry and Assembly Code



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 6)	V _{RRM} V _{RWM} V _R	600	V
RMS Reverse Voltage	V _{R(RMS)}	420	V
Average Rectified Output Current @ T _T = +75°C	lo	2.0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load		50	Α

Thermal Characteristics

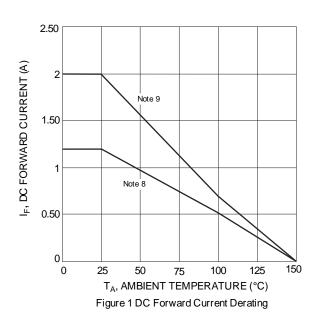
Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal	$R_{\Theta JT}$	22	°C/W
Operating and Storage Temperature Range	$T_{J_i} T_{STG}$	-55 to +150	°C

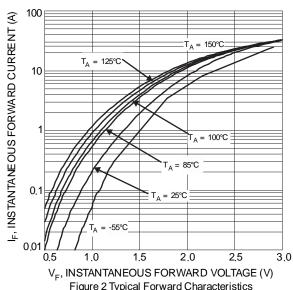
Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Minimum Reverse Breakdown Voltage (Note 6)	@ $I_R = 5\mu A$	$V_{(BR)R}$	600	V
Maximum Forward Voltage Drop	$@ I_F = 2.0A$	V_{F}	1.7	V
Peak Reverse Current	@ T _A = +25°C		5.0	uА
at Rated DC Blocking Voltage (Note 6)	@ $T_A = +100$ °C	IR	100	μΑ
Maximum Reverse Recovery Time (Note 7)		t _{RR}	75	ns
Typical Total Capacitance (Note 10)		Ст	10	pF

Notes:

- 6. Short duration pulse test used to minimize self-heating effect.
- 7. Measured with I_F = 0.5A, I_R = 1.0A, I_{RR} = 0.25A. See Figure 7.
- 8. Device mounted on FR-4 substrate, 1inch x 1inch, 2oz, single-sided, PC boards with 0.1inch x 0.15inch copper pads.
- 9. Device mounted on FR-4 substrate, 0.4inch × 0.5inch, 2oz, single-sided, PC boards with 0.2inch × 0.25inch copper pads.
- 10. Measured at f=1.0MHz and applied reverse voltage of 4.0V DC.









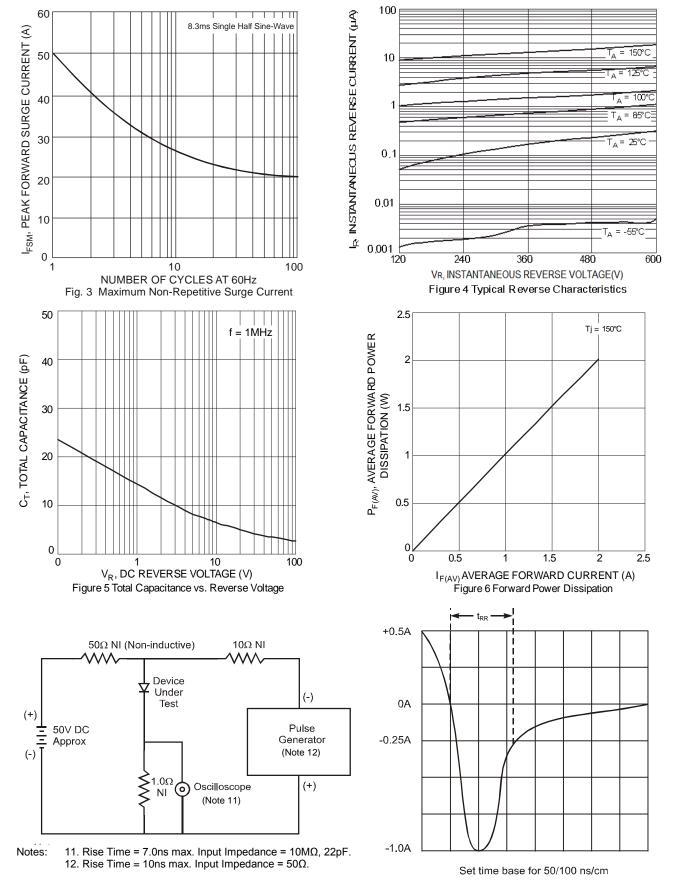


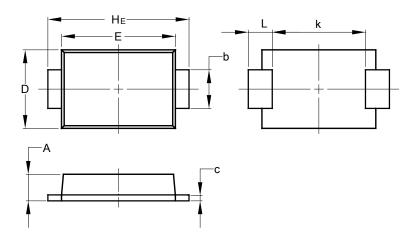
Figure 7 Reverse Recovery Time Characteristic and Test Circuit



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

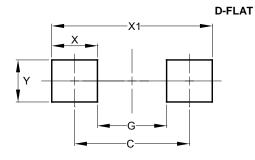
D-FLAT



	D EL AT			
D-FLAT				
Dim	Min	Max		
Α	0.90	1.10		
b	1.25	1.65		
C	0.10	0.40		
D	2.25	2.95		
Е	3.95	4.60		
k	2.80	_		
HE	5.00	5.60		
L	0.50	1.30		
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	4.65
G	2.80
X	1.85
X1	6.50
Υ	1.70



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